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TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSII)

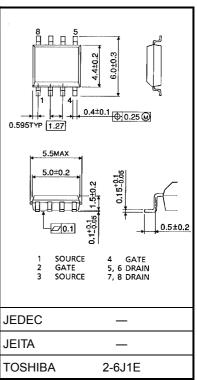
# **TPC8303**

Lithium Ion Battery Applications Portable Equipment Applications Notebook PCs

- Low drain-source ON resistance  $: R_{DS} (ON) = 27 \text{ m}\Omega (typ.)$
- High forward transfer admittance :  $|Y_{fs}| = 7 S (typ.)$
- Low leakage current  $: I_{DSS} = -10 \ \mu A \ (max) \ (V_{DS} = -30 \ V)$
- Enhancement-mode :  $V_{th} = -0.8 \sim -2.0 \text{ V} (V_{DS} = -10 \text{ V}, \text{ I}_D = -1 \text{ mA})$

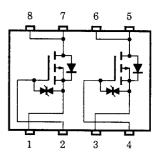
#### Maximum Ratings (Ta = 25°C)

Char	acteristics	Symbol	Rating	Unit	
Drain-source vol	tage	V <sub>DSS</sub>	-30	V	
Drain-gate voltag	ge (R <sub>GS</sub> = 20 k Ω )	V <sub>DGR</sub>	-30	V	
Gate-source volt	age	V <sub>GSS</sub>	±20	V	
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ ) $V_{DGR}$ -30	DC (Note 1)	۱ <sub>D</sub>	-4.5	А	
	A .				
	operation	P <sub>D (1)</sub>	1.5	W	
	at dual operation	P <sub>D(2)</sub>	1.0		
dissipation (t = 10s)	operation	P <sub>D (1)</sub>	0.75	W	
	at dual operation	P <sub>D (2)</sub>	0.45		
Single pulse ava	lanche energy (Note 4)	E <sub>AS</sub>	26	mJ	
Avalanche currei	nt	I <sub>AR</sub>	-4.5	А	
Single-device va		E <sub>AR</sub>	0.10	mJ	
Channel tempera	ature	T <sub>ch</sub>	150	°C	
Storage tempera	ture range	T <sub>stg</sub>	-55~150	°C	



Weight: 0.08 g (typ.)

# **Circuit Configuration**



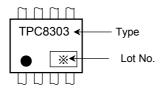
Note: For (Note 1), (Note 2a), (Note 2b), (Note 3a), (Note 3b), (Note 4) and (Note 5), please refer to the next page. This transistor is an electrostatic sensitive device. Please handle with caution.

Unit: mm

## **Thermal Characteristics**

Characteristics	Symbol	Max	Unit	
The mediate second to excluse	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	83.3	
Thermal resistance, channel to ambient (t = 10s) (Note 2a)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	125	°C/W
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	167	0/11
(t = 10s) (Note 2b)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	278	

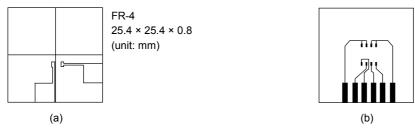
### Marking (Note 6)



Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:

- a) Device mounted on a glass-epoxy board (a)
- b) Device mounted on a glass-epoxy board (b)



FR-4 25.4 × 25.4 × 0.8 (unit: mm)

#### Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.)

Note 4: V<sub>DD</sub> = -24 V, T<sub>ch</sub> = 25°C (initial), L = 1.0 mH, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = -4.5 A

Note 5: Repetitive rating: pulse width limited by maximum channel temperature

Note 6:  $\bullet$  on lower left of the marking indicates Pin 1.



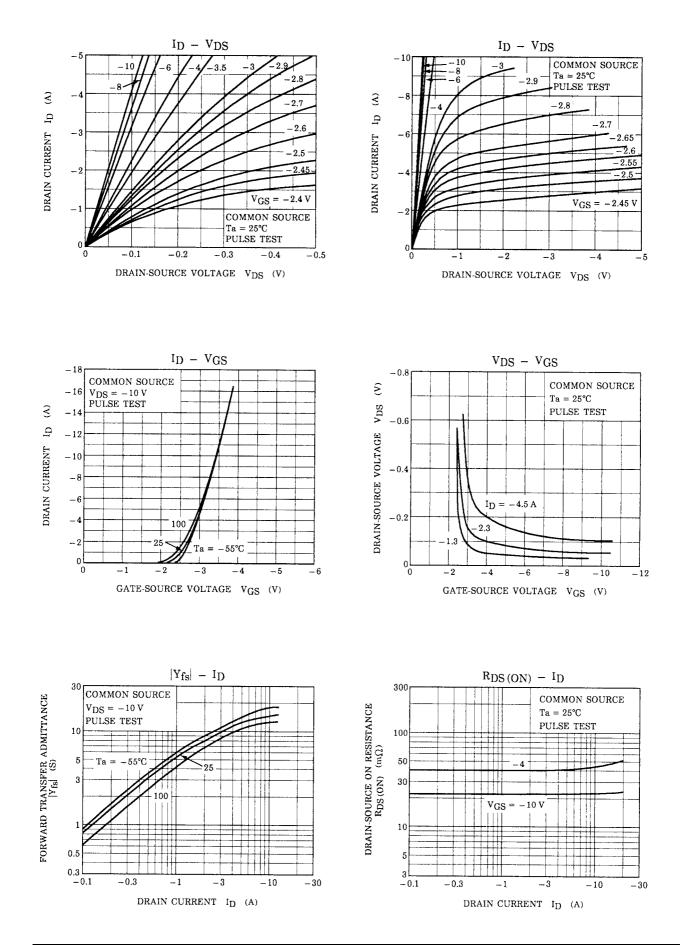
# Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	— — ±10		μA		
Drain cut-off cu	rrent	I <sub>DSS</sub>	$V_{DS}$ = -30 V, $V_{GS}$ = 0 V	-		— -10		
Drain-source br	eakdown voltage	V (BR) DSS	$I_{D}$ = -10 mA, $V_{GS}$ = 0 V	-30	_	_	v	
Dialit Source bi	eakdown voltage	V (BR) DSX	$I_{D}$ = -10 mA, $V_{GS}$ = 20 V	-15		_		
Gate threshold	/oltage	V <sub>th</sub>	$V_{DS}$ = -10 V, I <sub>D</sub> = -1 mA	-0.8		-2.0	V	
Drain-source O	Nresistance	R <sub>DS (ON)</sub>	$V_{GS}$ = -4 V, I <sub>D</sub> = -2.2 A		55	65	mΩ	
Dialit Source O	IN TESIStance	R <sub>DS (ON)</sub>	$V_{GS}$ = -10 V, I <sub>D</sub> = -2.2 A	-      27      35        3.5      7      -		35	11132	
Forward transfe	r admittance	Y <sub>fs</sub>	$V_{DS}$ = -10 V, I <sub>D</sub> = -2.2 A	3.5	7	-	S	
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = –10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		970	-	pF	
Reverse transfer capacitance		C <sub>rss</sub>		_	180	_		
Output capacitance		C <sub>oss</sub>		_	370	_		
Switching time	Rise time	tr	$V_{GS} \xrightarrow{0 V} I_{D} \xrightarrow{I_{D} = -2.2 A} V_{OUT}$		17	_		
	Turn-ON time	t <sub>on</sub>		-	20	_		
	Fall time	t <sub>f</sub>		-	75	_	ns	
	Turn-OFF time	t <sub>off</sub>	$V_{DD} = -15 V$ Duty $\leq 1\%$ , $t_w = 10 \ \mu s$		160	_		
Total gate charge (Gate-source plus gate-drain)		Qg	$V_{DD} \approx -24 \text{ V}, \text{ V}_{GS} = -10 \text{ V}, \text{ I}_{D} = -4.5 \text{ A}$	_	28	—		
Gate-source charge		Q <sub>gs</sub>		_	16	—	nC	
Gate-drain ("miller") charge		Q <sub>gd</sub>		—	12	-		

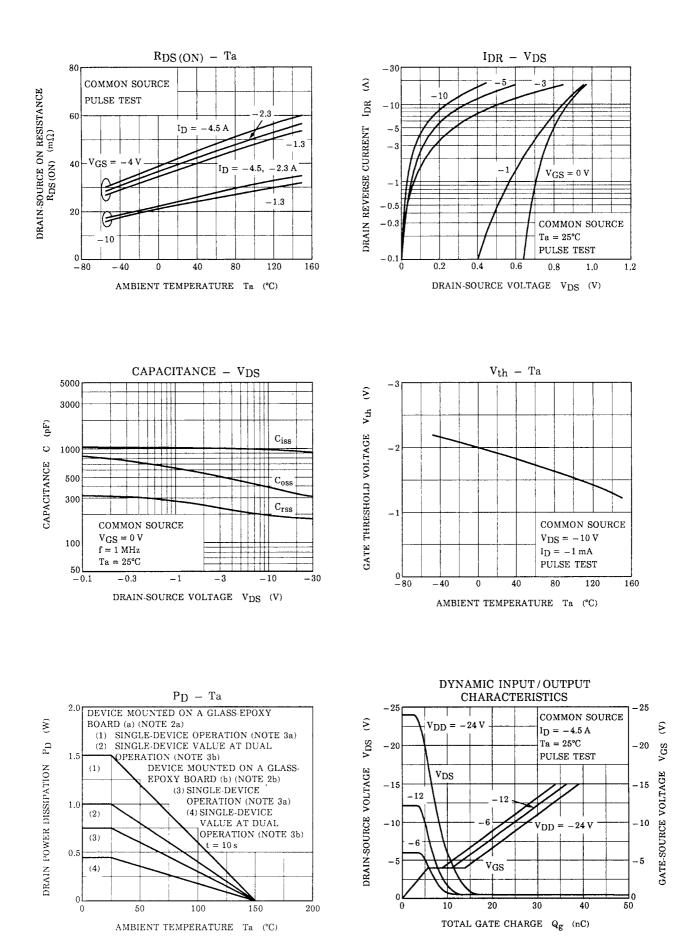
# Source–Drain Ratings and Characteristics (Ta = 25°C)

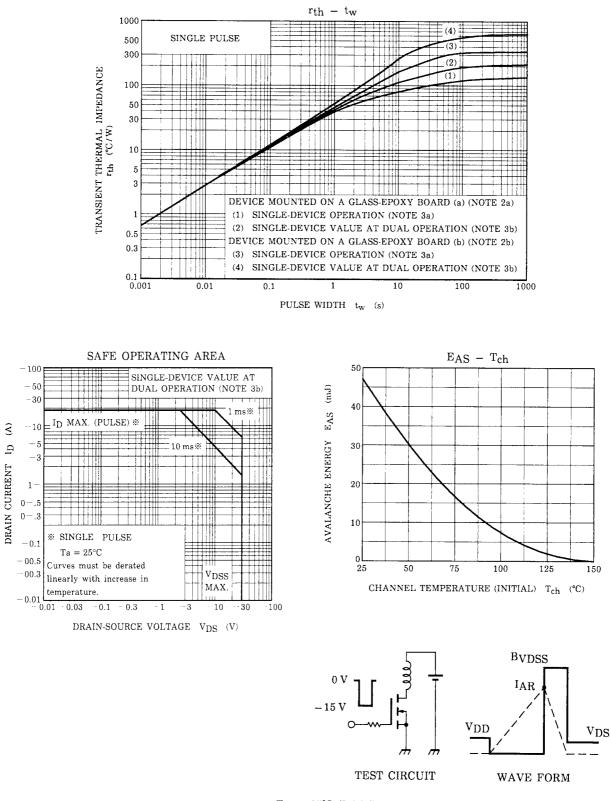
Charact	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	Ι	Ι	-18	A
Forward voltage	(diode)	V <sub>DSF</sub>	I <sub>DR</sub> = -4.5 A, V <sub>GS</sub> = 0 V	_	_	1.2	V

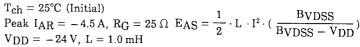
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